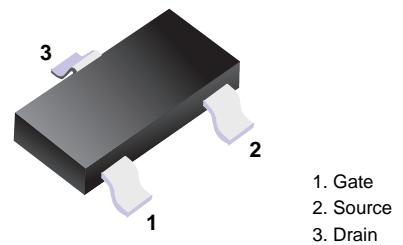


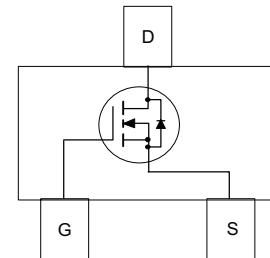
■ N-Channel MOSFET



■ Features

- $V_{DS(V)} = 30 \text{ V}$
- $I_D = 2.2 \text{ A}$
- $R_{DS(ON)} = 0.065 \Omega @ V_{GS} = 4.5 \text{ V}$
- $R_{DS(ON)} = 0.082 \Omega @ V_{GS} = 2.5 \text{ V}$

■ Simplified outline(SOT-23)



■ Absolute Maximum Ratings  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current	$I_D$	2.2	A
Pulsed Drain Current	$I_{DM}$	10	
Power Dissipation (Note 1a) (Note 1b)	$P_D$	0.5	W
		0.46	
Thermal Resistance.Junction- to-Ambient (Note 1a)	$R_{thJA}$	250	$^\circ\text{C}/\text{W}$
Thermal Resistance.Junction- to-Case (Note 1)	$R_{thJC}$	75	
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to 150	

Notes:

1.  $R_{thJA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{thJC}$  is guaranteed by design while  $R_{thCA}$  is determined by the user's board design.

- a.  $250^\circ\text{C}/\text{W}$  when mounted on a  $0.02 \text{ in}^2$  pad of 2oz Cu.
- c.  $270^\circ\text{C}/\text{W}$  when mounted on a  $0.001 \text{ in}^2$  pad of 2oz Cu.

■ Electrical Characteristics  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D=250 \mu\text{A}, V_{GS}=0\text{V}$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$		1		$\mu\text{A}$
		$V_{DS}=24\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$		10		
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$	0.4	1		V
Static Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS}=4.5\text{V}, I_D=2.2 \text{ A}$		65		$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=2.2 \text{ A}, T_J=125^\circ\text{C}$		110		
		$V_{GS}=2.5\text{V}, I_D=2 \text{ A}$		82		
On State Drain Current	$I_{D(\text{ON})}$	$V_{GS}=4.5 \text{ V}, V_{DS}=5 \text{ V}$	10			A
Forward Transconductance	$g_{FS}$	$V_{DS}=5 \text{ V}, I_D=2.2 \text{ A}$		13		S
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=10\text{ V}, f=1\text{MHz}$		300		$\text{pF}$
Output Capacitance	$C_{oss}$			145		
Reverse Transfer Capacitance	$C_{rss}$			35		
Total Gate Charge	$Q_g$	$V_{GS}=4.5 \text{ V}, V_{DS}=10 \text{ V}, I_D=2.2 \text{ A}$		7	9	$\text{nC}$
Gate Source Charge	$Q_{gs}$			1.1		
Gate Drain Charge	$Q_{gd}$			1.9		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=4.5 \text{ V}, V_{DD}=5 \text{ V}, I_D = 1\text{A}, R_{GEN}=6\Omega$		4	10	$\text{ns}$
Turn-On Rise Time	$t_r$			10	18	
Turn-Off Delay Time	$t_{d(off)}$			17	28	
Turn-Off Fall Time	$t_f$			4	10	
Maximum Body-Diode Continuous Current	$I_s$				0.42	A
Diode Forward Voltage	$V_{SD}$	$I_s=0.42 \text{ A}, V_{GS}=0\text{V}$ (Note 2)			1.2	V

Note 2: Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$

■ Typical Characteristics

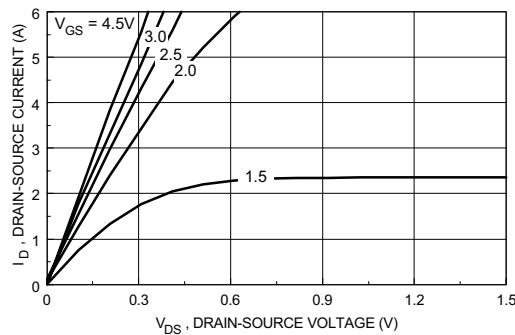


Figure 1. On-Region Characteristics.

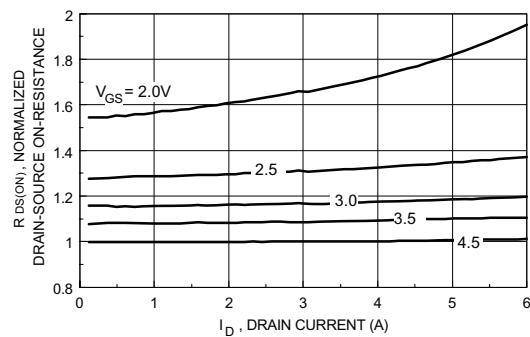


Figure 2. On-Resistance Variation with Drain Current and Gate

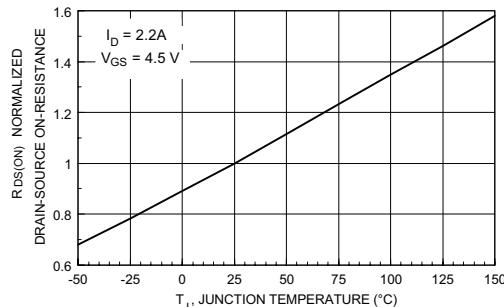


Figure 3. On-Resistance Variation with Temperature.

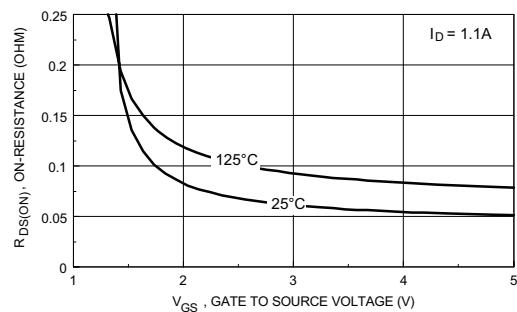


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

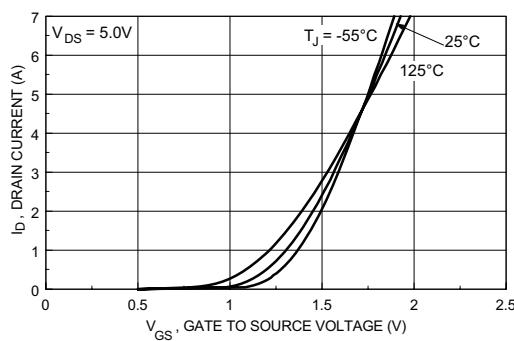


Figure 5. Transfer Characteristics.

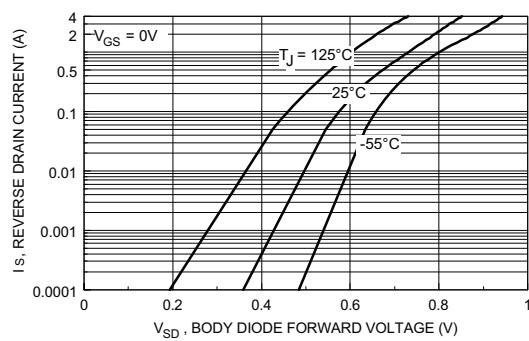


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

■ Typical Characteristics

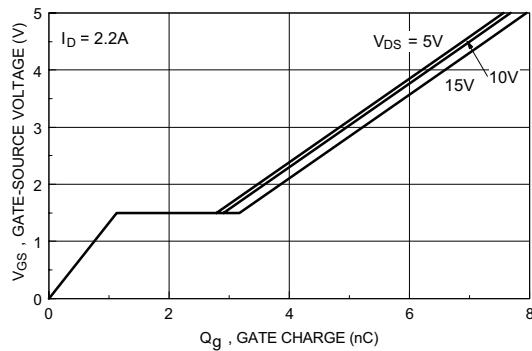


Figure 7. Gate Charge Characteristics.

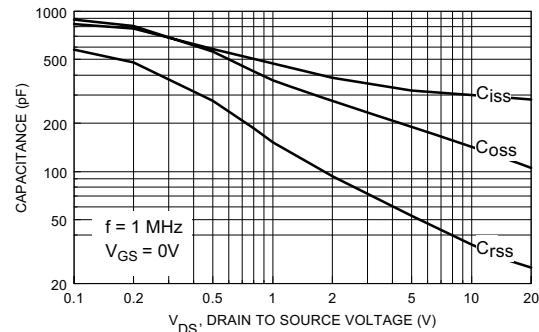


Figure 8. Capacitance Characteristics.

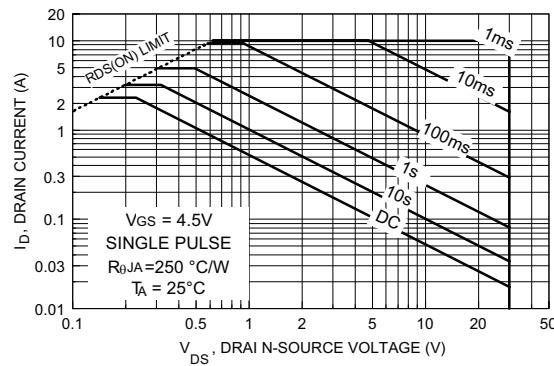


Figure 9. Maximum Safe Operating Area.

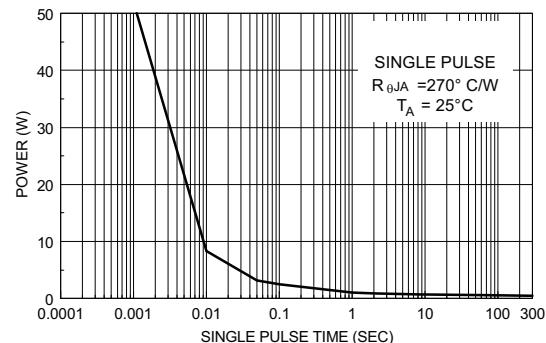


Figure 10. Single Pulse Maximum Power Dissipation.

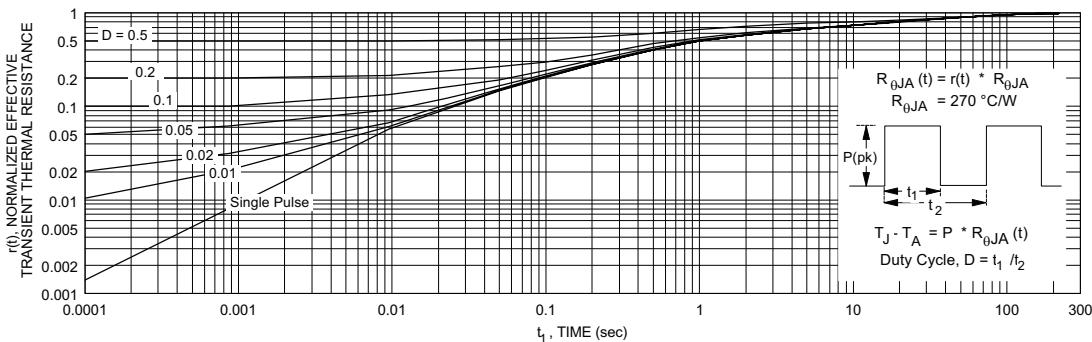
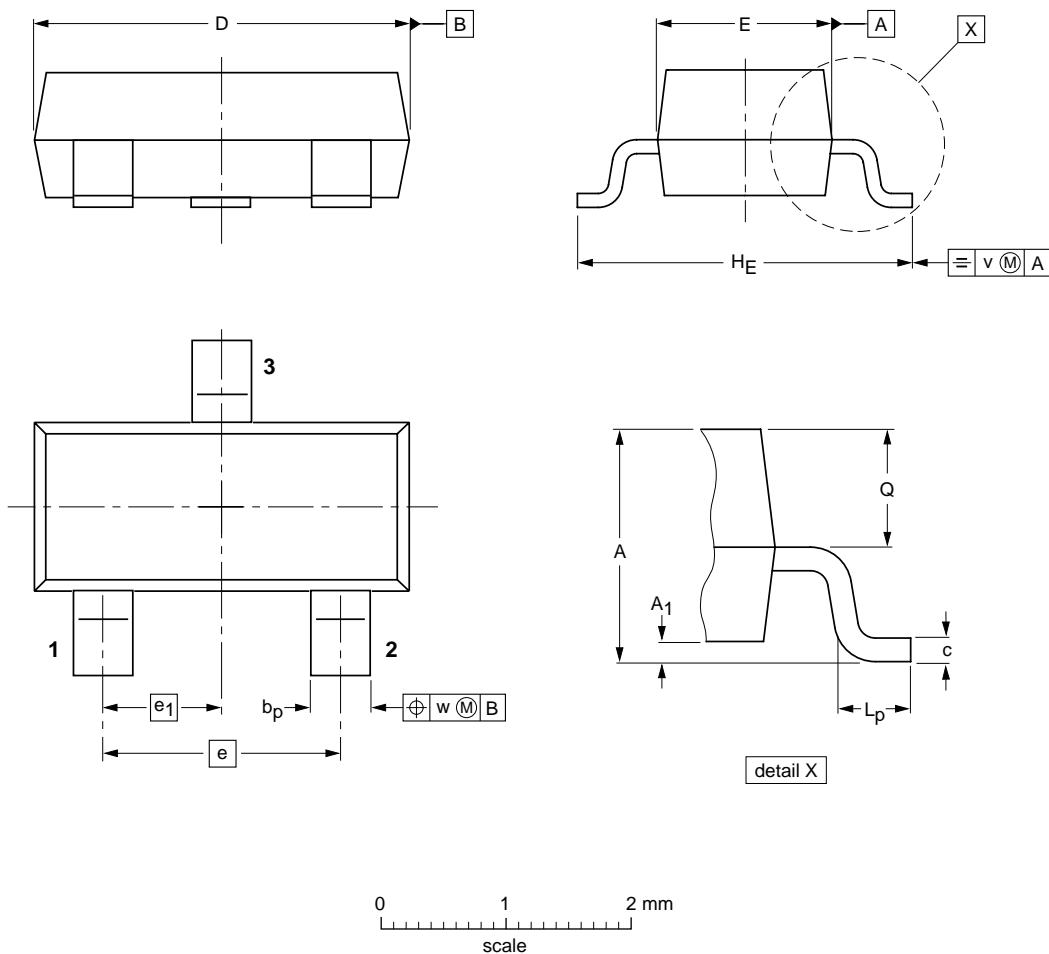


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in note 1b.  
Transient thermal response will change depending on the circuit board design.

■ SOT-23



DIMENSIONS (mm are the original dimensions)

UNIT	A	$A_1$ max.	$b_p$	c	D	E	e	$e_1$	$H_E$	$L_p$	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1